

Filename: PMP2661REVA_bom.xls						
Date: 08/01/2008						
PMP2661REVA BOM						
COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C1	680uF	Capacitor, Alum, 680uF, 25V, 23 milliohm	0.315 inch	25ZL680M10X20	Rubycon
1	C2	10uF	Capacitor, Ceramic, 10uF, 25V, X5R	1206	C3216X5R1E106MT	TDK
1	C3	0.1uF	Capacitor, Ceramic, 50V, X7R, 15%	0603	std	TDK
1	C4	560pF	Capacitor, Ceramic, 50V, X7R, 15%	0603	Std	TDK
2	C5	1000uF	Capacitor, Alum, 1000uF, 16V, 23 milliohms	0.315 inch	16ZL1000M10x20	Rubycon
	C6	1000uF	Capacitor, Alum, 1000uF, 16V, 23 milliohms	0.315 inch	16ZL1000M10x20	Rubycon
1	C7	10uF	Capacitor, Ceramic, 10uF, 25V, X5R	1206	C3216X5R1E106M	TDK
2	C8	1uF	Capacitor, Ceramic, 16V, X7R, 15%	0603	std	TDK
1	C9	470pF	Capacitor, Ceramic, 50V, X7R, 15%	0603	std	TDK
	C10	1uF	Capacitor, Ceramic, 16V, X7R, 15%	0603	std	TDK
1	C11	330pF	Capacitor, Ceramic, 50V, X7R, 15%	0603	std	TDK
1	C12	47nF	Capacitor, Ceramic, 50V, X7R, 15%	0603	std	TDK
1	C13	1nF	Capacitor, Ceramic, 50V, X7R, 15%	0603	std	TDK
1	D1	MBR30H30CTG	Diode, Dual Schottky, 30V, 30A	TO-220V	MBR30H30CTG	ONsemi
1	HS1	SK 437 35 STC 2	Heatsink, TO-220/218 veritcal, Rth 18K/W	0.640 x 0.640 inch	SK 437 35 STC 2 and THF 409 220 2	Fischer Elektronik
2	J1	D120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	D120/2DS	OST
	J2	D120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	D120/2DS	OST
1	L1	4.7uH	Inductor, SMT, 4.7uH, 10A, 15milliohm	0.51 x 0.51 inch	IHLP5050FDER4R7M01	Vishay
1	Q1	Si7686DP	MOSFET, NCh, 30V, 35A, 10 millohm	PWRPAK S0-8	Si7686DP	Vishay
1	R1	10	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R2	392K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R4	10	Resistor, Chip, 1/4W, 1%	1206	Std	Std
1	R5	1K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R6	0.005	Resistor, 5 milliOhm, 2W, 1%	2512	2.32276E+11	Phycomp
1	R7	19.1K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R8	24.9K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R9	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R10	2.0K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
	R11	10	Resistor, Chip, 1/4W, 1%	1206	Std	Std
1	TP1	VIN	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
2	TP2	GND	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	TP3	VOUT	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone

1	TP4	SW	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
	TP5	GND	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
2	TP7	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
	TP8	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	U1	TPS40210DGQ	IC, 4.5V-52V I/P, Current Mode Boost Controller	DGQ10	TPS40210DGQ	TI
Notes:	1. These assemblies are ESD sensitive, ESD precautions shall be observed.					
	2. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.					
	3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.					
	4. Ref designators marked with an asterisk (***) cannot be substituted.					
	All other components can be substituted with equivalent MFG's components.					

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